

## 1<sup>st</sup> Annoucement

The 4<sup>th</sup> International Conference on Engineering Physics, MEMS-  
Biosensors and Applications (4<sup>th</sup> ICEBA2023)  
*December 8&9,2023; Ho Chi Minh city, Vietnam*  
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### 1. The scope of Conference

The purpose of the 4<sup>th</sup> ICEBA2023 is to link the researchers, scientists from Vietnam, Australia and Asian countries in the field of Engineering Physics and microelectronics and semiconductors for their applications in biomedical engineering, health sciences, hi-tech agriculture and smart cities. Besides, we also contribute to promoting international cooperation activities on join research projects and international co-publications.

### 2. The subject areas

Contributed papers must be the new research works and are solicited in the following subject areas (but not limited to):

- *Applied Physics, Engineering Physics, Electronic Engineering and Nuclear Engineering;*
- *MEMS (MicroElectronMechanical System), Sensors, Biosensors and semiconducting devices;*
- *Microelectronics, IC design, low consumption devices, Renewable Energy*
- *Computing Science, Simulations and Modeling;*
- *Embedded systems, Internet of Things, Machine Learning, Artificial Intelligence,..*
- *Biomedical Engineering, Digital Microfluidics and their applications;*

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### 3. Time: 02 days

- December 8<sup>th</sup> (Sat): Registration, Opening Ceremony & Plenary talks, Poster session, Parallel sessions, Meeting of 5<sup>th</sup> ICEBA2024 and Conference party.
- December 9<sup>th</sup> (Sun): Tutorial Session and City tour.

**4. Venue:** VNUHCM-University of Science, 227 Nguyen Van Cu Str., Dist. 5, Ho Chi Minh city, Vietnam.

**5. Co-organizers:** University of Science (VNUHCM, Vietnam) and Tohoku University (Japan)

**6. Technical Supports:** IEEE Vietnam Section, Institute Electrical Engineer of Japan (IEEJ, Japan), Institute of Korean Electrical& Electronic Engineers (IKEEE, Korea) and HoChiMinh Semiconducting Industrial Association (HSIA).

### 7. Publications:

The selected papers (from 4 to 8 pages) will be reviewed or recommended for the publications in one of the below Scopus/SCIE/Scimago database Journal *with your payment* such as:

- (1) IEEJ Transactions on Electrical and Electronic Engineering (Scopus, Q3);
- (2) IEEJ Transactions on Sensors and Micromachines (Scopus, Q4) ;
- (3) Applied Sciences (MDPI, Scopus, IF: 2.9, Q1/Q2);
- (4) Special Issue of Nanomaterials (MDPI, Scopus, IF:5.3, Q1);

## **8. Co-General Chair:**

- . Takahito Ono, *Tohoku University-Japan*
- . Nguyen Van Hieu, *Vietnam National University HoChiMinh City*

## **9. Committees of 4<sup>th</sup> ICEBA2023:**

### **\* Scientific Committee:**

- . Takahito Ono, *Tohoku University-Japan*
- . Chau Van Tao, *VNUHCM-University of Science-Vietnam*
- . Masaya Toda, *Tohoku University- Japan*
- . Do Hong Tuan, *VNUHCM-UT & IEEE Vietnam Section*
- . Nguyen Van Hieu, *Vietnam National University HCMC*
- . Le Vu Tuan Hung, *VNUHCM-University of Science-Vietnam*
- . Phan Bach Thang, *VNUHCM-INOMAR-Vietnam*
- . Kyeong-Sik Min, *Kookmin University& IKEEE-Korea*
- . Ching Tak Shing Congo, *National Chung Hsing University-Taiwan (R.O.C)*
- . Jen-Inn Chyi, *National Central University- Taiwan (R.O.C)*
- . Kun-Yu Lai, *National Central University-Taiwan (R.O.C)*
- . Nguyen Hoang Nam, *VNU Ha Noi-University of Science-Vietnam*

### **\*Program Committee:**

- . Huynh Van Tuan , *VNUHCM-University of Science-Vietnam, Chair*
- . Nguyen Van Toan, *Tohoku University-Japan, Co-chair*
- . Tran Thien Thanh, *VNUHCM-University of Science-Vietnam*
- . Hoang Trang, *VNUHCM-University of Technology- Vietnam*
- . Huynh Chan Khon, *VNUHCM-International University-Vietnam*
- . Vu The Dang, *Osaka Metropolitan University- Japan*
- . Dau Van, *Griffith University-Australia*
- . Nguyen Chi Nhan, *VNUHCM-University of Science-Vietnam*
- . Nguyen Van Men, *VNUHCM- An Giang University-Vietnam*
- . Truong Thi Kim Tuoi, *Tohoku University-Japan*
- . Nguyen Quang Khoi, *VNUHCM-US Vietnam*
- . Nguyen Chi Linh, *VNUHCM-US Vietnam*

### **\*Publication Committee:**

- . Takahito Ono, *Tohoku University-Japan*
- . Nguyen Van Hieu, *Vietnam National University HCMC, Vietnam*
- . Huynh Van Tuan, *VNUHCM-University of Science-Vietnam*

### **\* Local Organizing Committee:**

- . Nguyen Chi Nhan, *VNUHCM-US Vietnam, Chair*

- . Vo Hong Hai, *VNUHCM-US Vietnam, Co-chair*
- . Ho Thanh Huy, *VNUHCM-US Vietnam*
- . Huynh Thanh Nhan, *VNUHCM-US Vietnam*
- . Do Duc Cuong, *VNUHCM-US Vietnam*
- . Trinh Thi Ly, *VNUHCM-US Vietnam*
- . Nguyen Hoang Quan, *VNUHCM-US Vietnam*
- . Phan Thien Luan, *NCHU-Taiwan (R.O.C)*

**\*Secretariats:**

- . Nguyen Phuoc Hoang Khang, *VNUHCM-US Vietnam*
- . Hua Thi Hoang Yen, *VNUHCM-US Vietnam*
- . Nguyen Vuong Thuy Ngan, *VNUHCM-US Vietnam*

**8. Plenary talks and Invited speakers**

- Prof. Takahito Ono, *Tohoku University-Japan*
- Prof. Kyeong-Sik Min, *Kookmin University- Korea*
- Prof. Dao Viet Dzung, *Griffith University- Australia*
- Prof. Ching Tak Shing Congo, *National Chung Hsing University-Taiwan (R.O.C)*
- Prof. Kun-Yu Lai, *National Central University- Taiwan (R.O.C)*

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*(will be updated)*

**9. Sessions of 4<sup>th</sup> ICEBA2023:** There are 05 sections for parallel sessions and 01 poster session:

**\*Oral Sessions:**

- . Session 1. Applied Physics, Engineering Physics, Nuclear Engineering
- . Session 2. MEMS, Biosensors and Application
- . Session 3. Microelectronics, Embedded System and AI&IoT
- . Session 4. Computing Science, Simulation and Modeling
- . Session 5. Biomedical Engineering and Medical devices

**\* Poster Session:** for above 5 sessions

**10. Conference fee registration for authors** (for abstract book, coffee break, meals):

- Plenary, Invited speakers, Program committee, Scientific committee: *Free of charge*
- Professors, researchers, lecturers: 100 USD (*2.000.000 VNĐ for Vietnamese*)
- Students and belong: 50usd (*1.000.000 VNĐ for Vietnamese*)
- Bank account Transfer:
  - . *Bank Account (US dollar and VN dong): ICEBA2023*
  - . *Name of Account holder: HUYNH THANH NHAN*
  - . *Bank name: Joint Stock Commercial Bank for Investment and Development of Vietnam*
  - . *Swift code: BIDVNVX*

**11. The deadline:**

- Abstract submission and registration: October 30<sup>th</sup>, 2023
- Full paper submission for presentaion: November 15<sup>th</sup>, 2023
- Conference payment fee: Before November 15<sup>th</sup>, 2023

- Session schedule announcement: November 20<sup>th</sup>, 2023
- Conference day: December 8&9<sup>th</sup>, 2023
- Full paper submission for publication: December 30<sup>th</sup>, 2023

## **12. Contact for 4<sup>th</sup>ICEBA2023:**

### **The Secretary**

Address: 227 Nguyen Van Cu Street, District 5, Ho Chi Minh city, Vietnam.

Email: 4iceba2023@gmail.com

Contact: Office of Faculty of Physics and Engineering Physics, A Building

Website: <https://phys.hcmus.edu.vn/ICEBA2023/#/>

**4<sup>th</sup>ICEBA2023**